

The Devolution of Synchronizers

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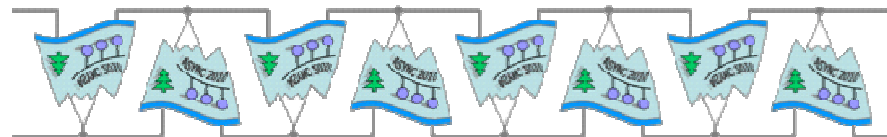
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Outline

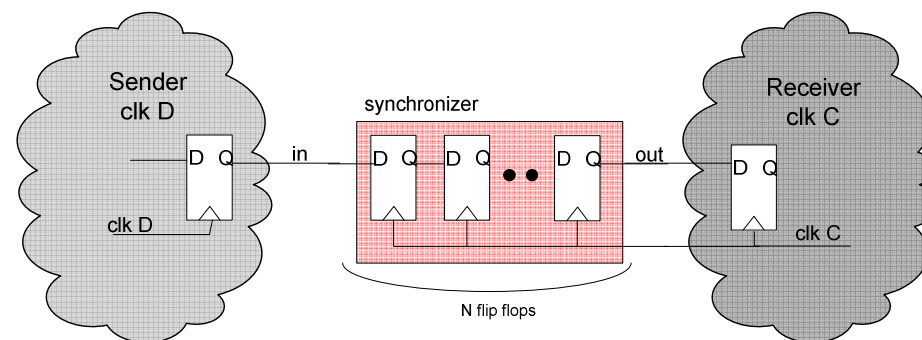
- **Introduction**
- First signs of devolution
 - ◆ SoC measurements
- Further Confirmation of devolution
 - ◆ FPGA measurements
- How can we explain devolution
 - ◆ Model
- Implications & Conclusions

Synchronizers

- ▶ Simple failure rate model of latches and FF

$$MTBF = \frac{e^{S/\tau}}{T_W \times F_C \times F_D}$$

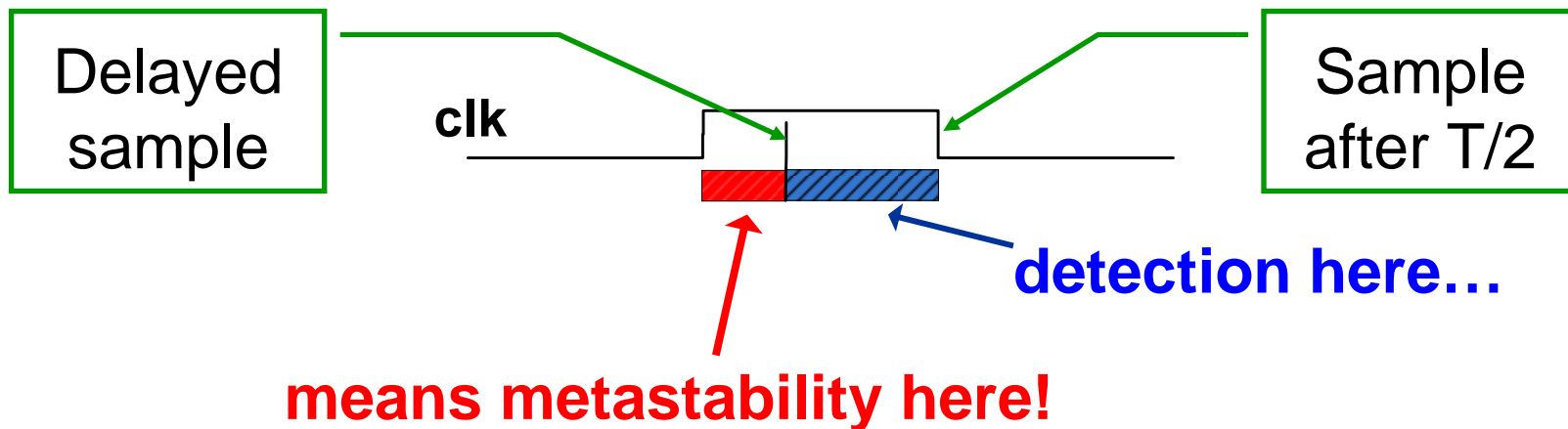
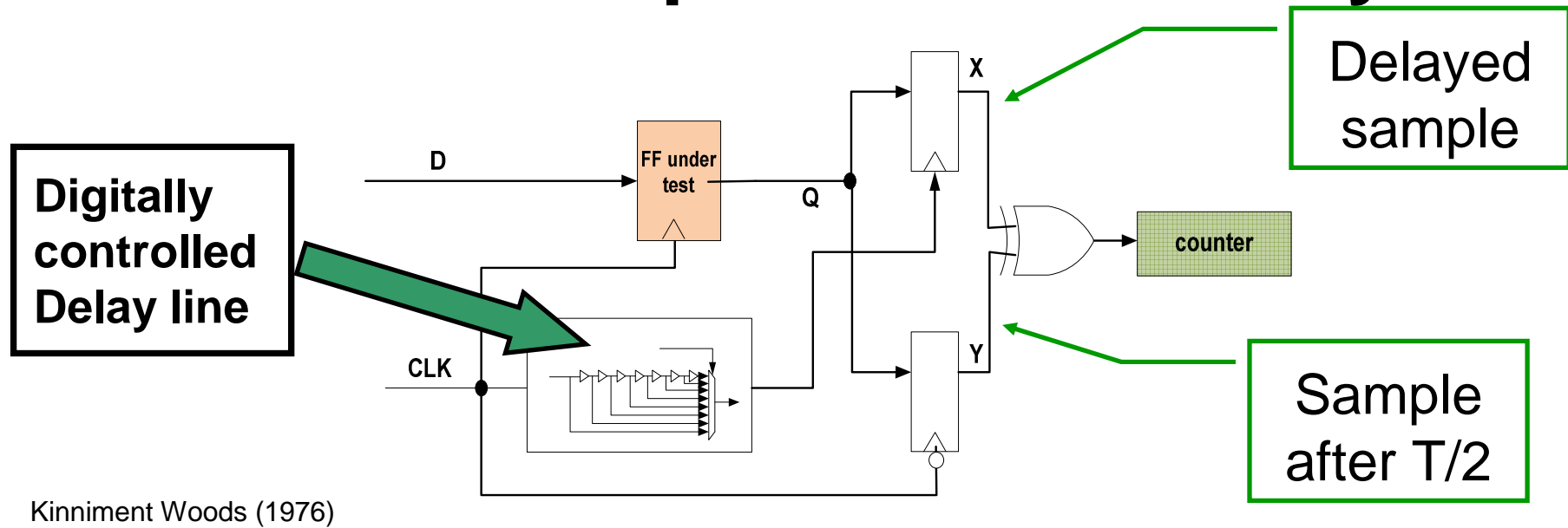
- ▶ Synchronizer performance figure of merit (τ dominant)
 - Fast recovery (low τ) → Good synch.
 - Slow recovery (high τ) → Bad synch
- ▶ τ was believed to scale down with technology
- ▶ Rule of thumb to design “reliable” synch was : $\tau \approx 2 \cdot FO4$



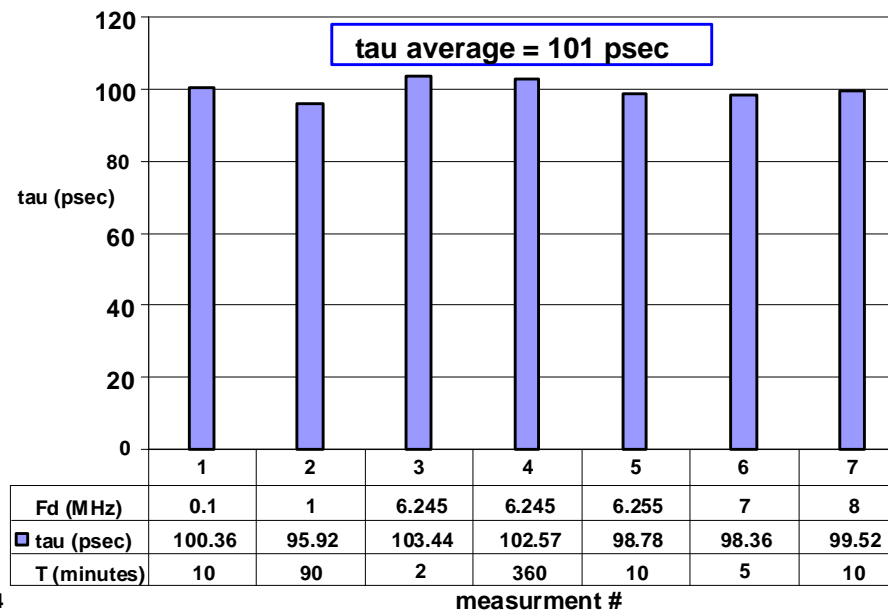
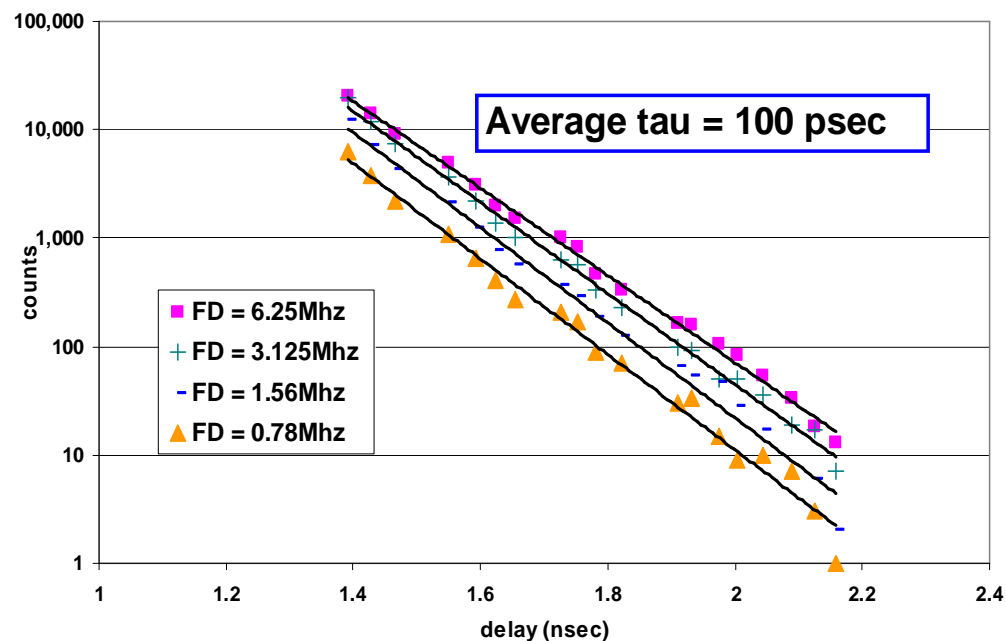
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On-chip measurement system



Measurement Results

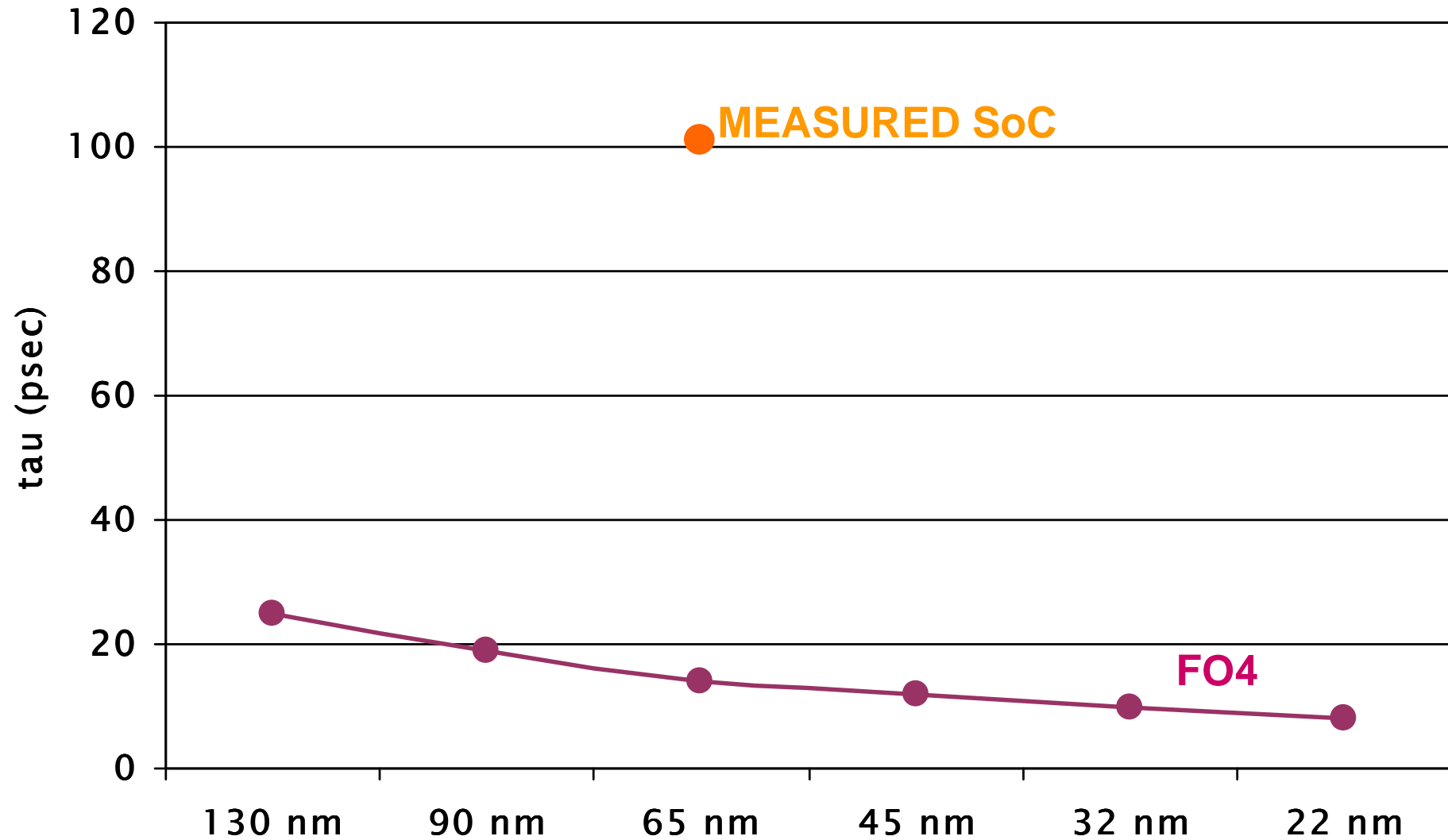


Tau values higher than expected

First signs of devolution

- ▶ A 65nm bulk CMOS TC fabricated
- ▶ τ for several FF measured using on-chip measurement system.
- ▶ Measured: $\tau \sim 100 \text{ psec}$
- ▶ Expected: $\tau \sim 56 \text{ psec}$
 - *F04 of LP 65nm* $\sim 28 \text{ psec}$

Unified graph of τ trend

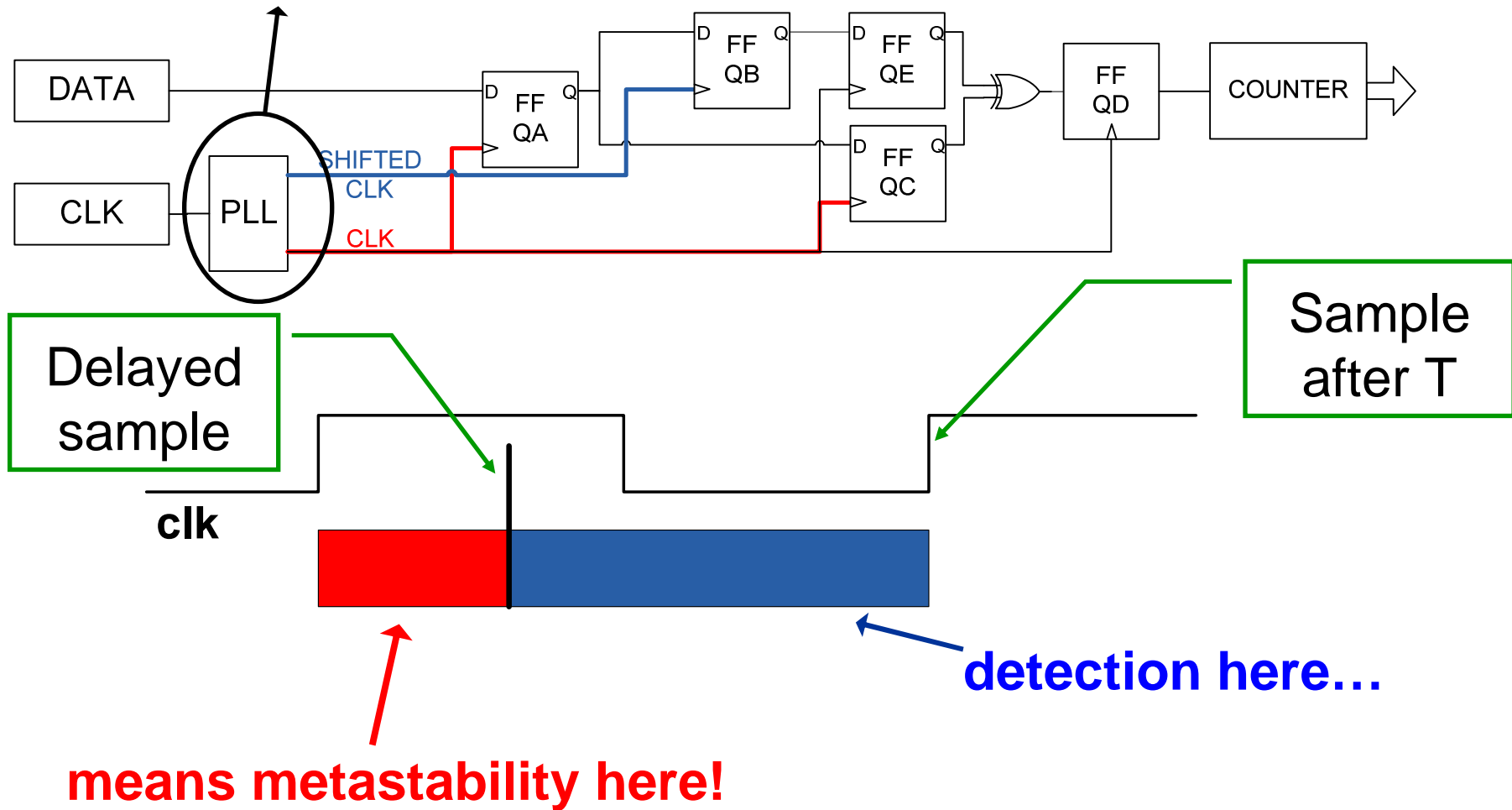


Outline

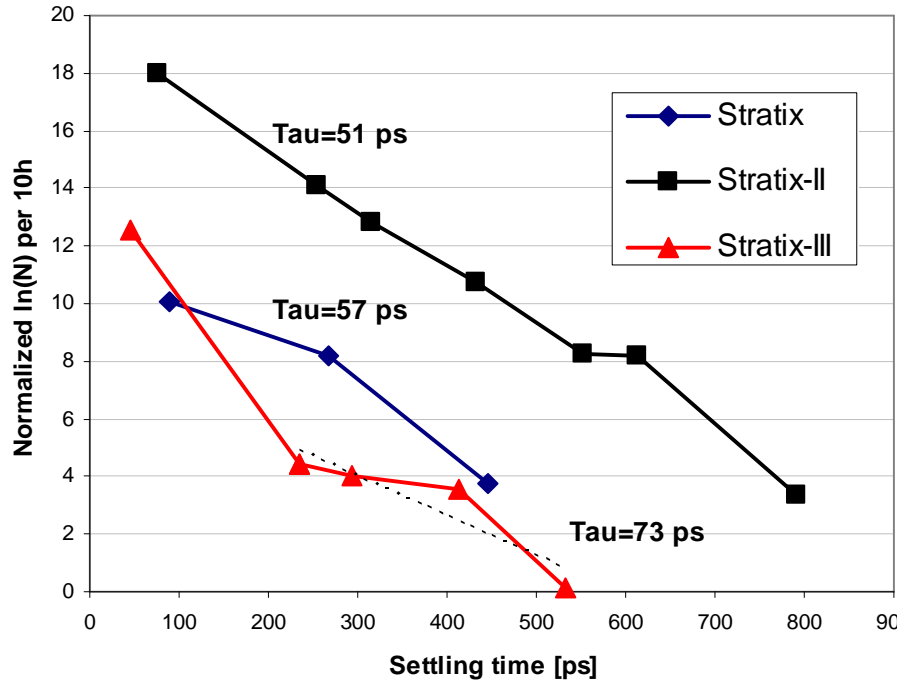
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Measurement method

Phase shifted PLL instead of delay line

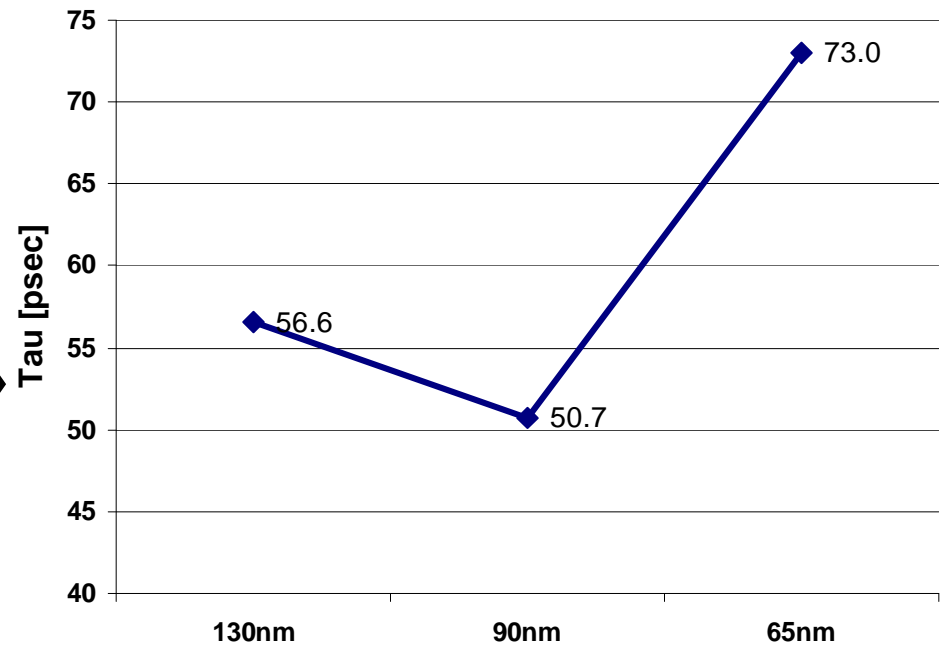


Altera FPGA results



← exponential behavior

scaling degradation →

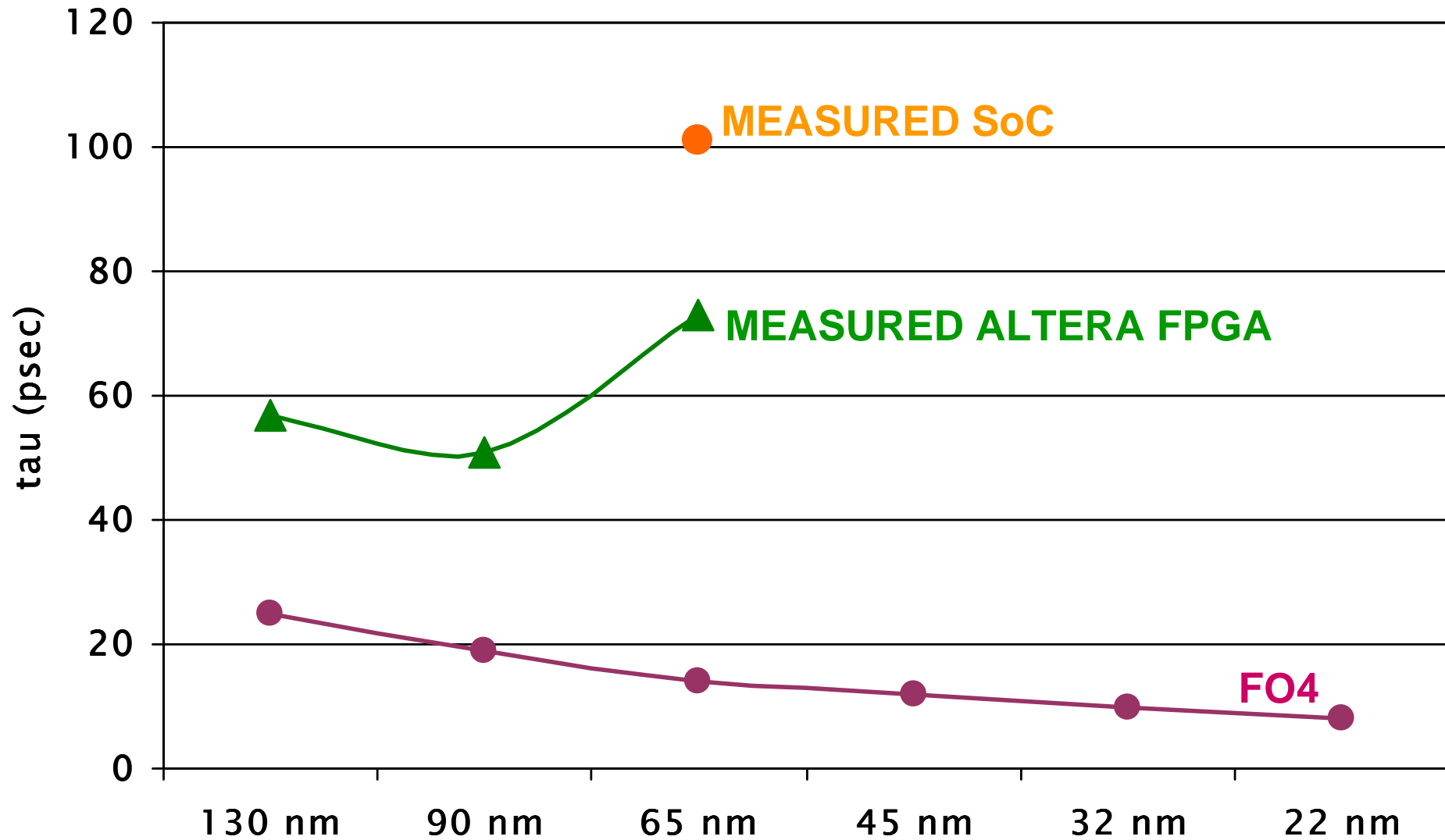


Altera FPGA Measurements

- ▶ Three generations of similar FPGA devices measured:
 - Stratix (130 nm)
 - Stratix II (90 nm)
 - Stratix III (65 nm)

- ▶ Internal LAB/CLB FF was used as synchronizer
- ▶ Measuring method similar to SoC, under FPGA constraints
- ▶ Internal delay compensated

Unified graph of τ trend



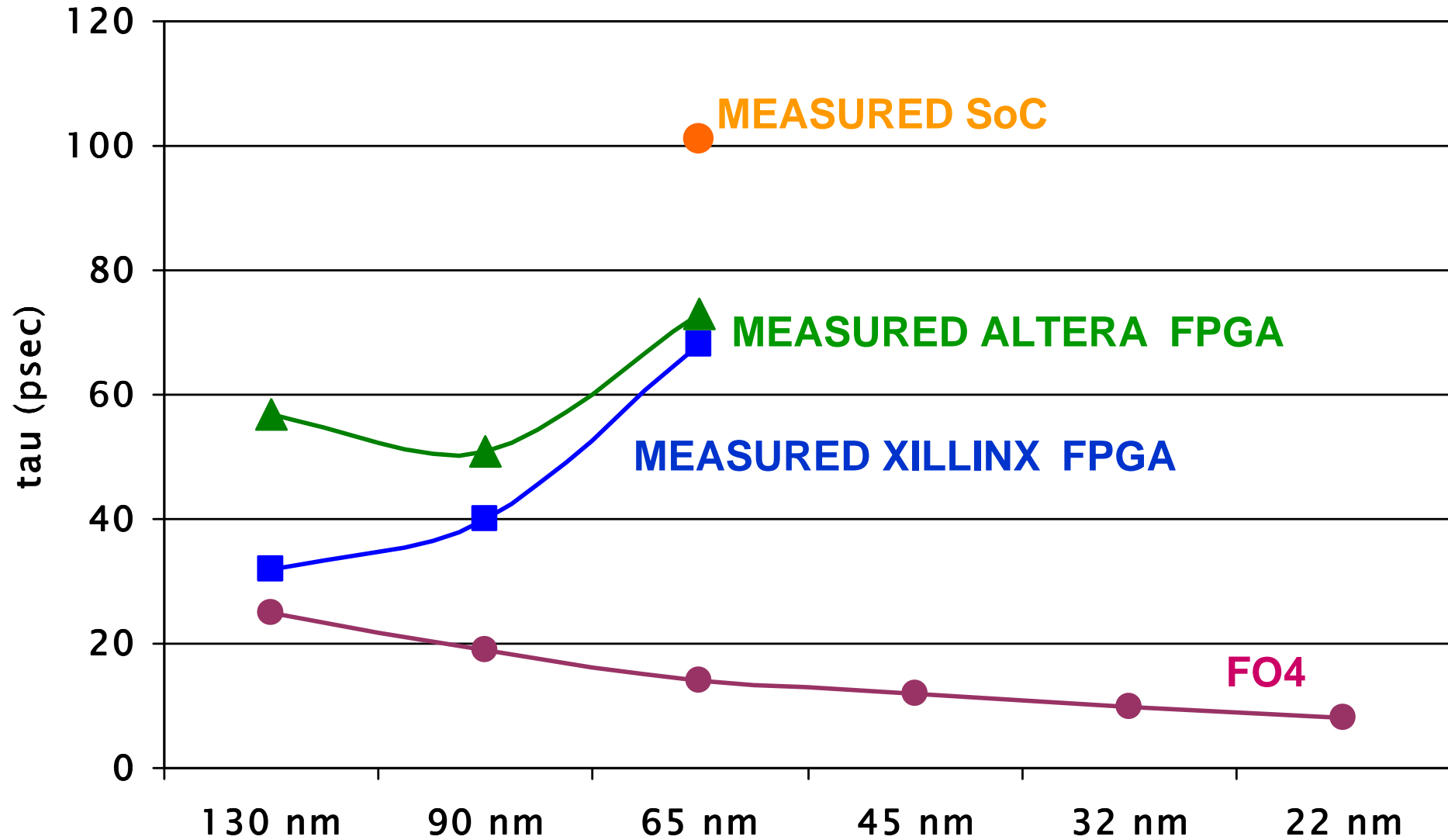
Xilinx FPGA Measurements

- ▶ P. Alfke measured 3 generations of devices:
 - Virtex II-pro (130 nm)
 - Virtex 4 (90 nm)
 - Virtex 5 (65 nm)

- ▶ Internal FPGA FF were measured

- ▶ Different measuring method
 - Varying frequency instead of delay

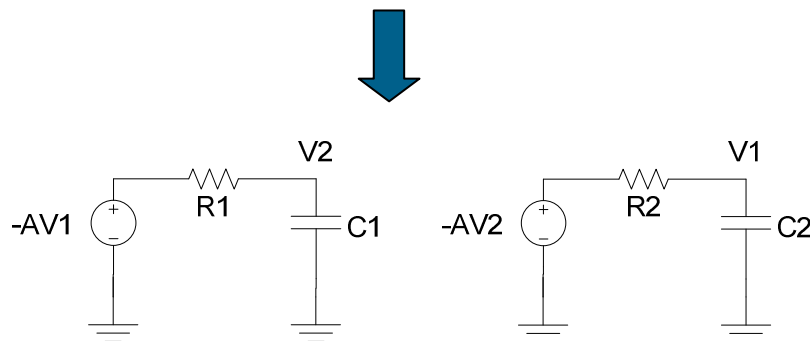
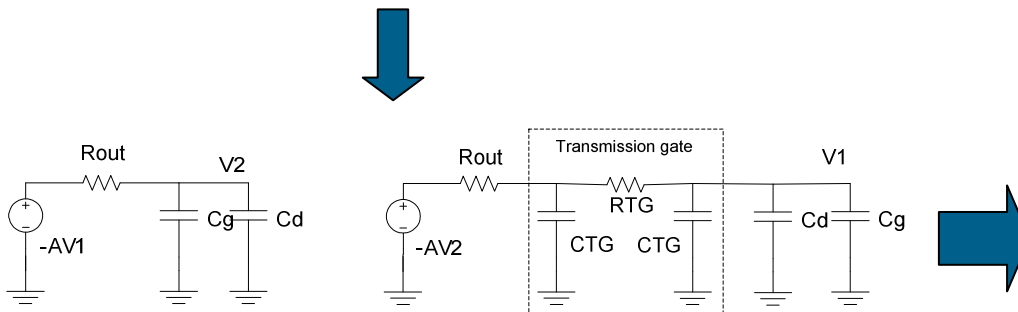
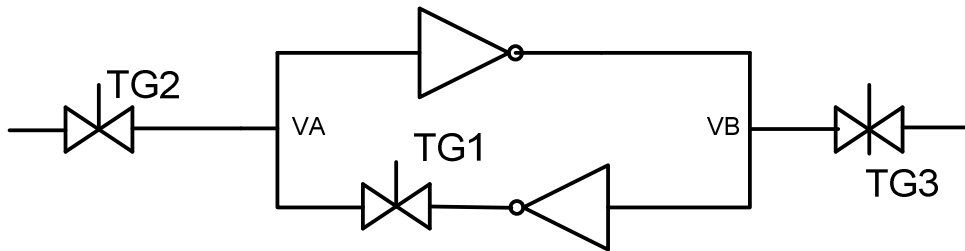
Unified graph of τ trend



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Latch Model



$$\tau = \frac{\eta}{4} \frac{FO4}{A}$$

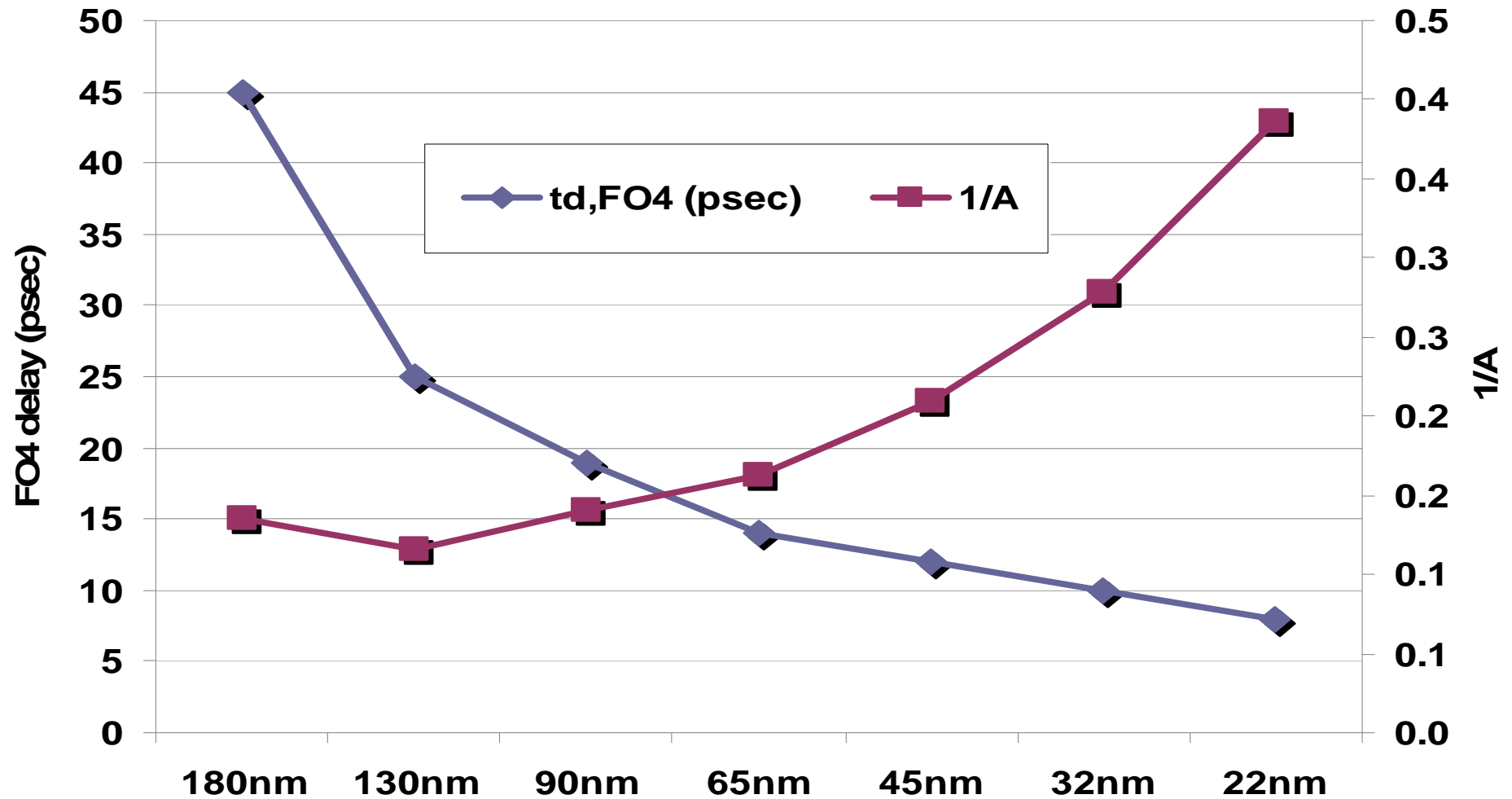
$$\eta \approx \frac{2}{3} \frac{1}{\lambda \cdot V_{DD}} \left(\frac{V_{DD} - V_T}{\frac{V_{DD}}{2} - V_T} \right)$$

λ Channel length modulation (CLM)

Two new factors, η and A

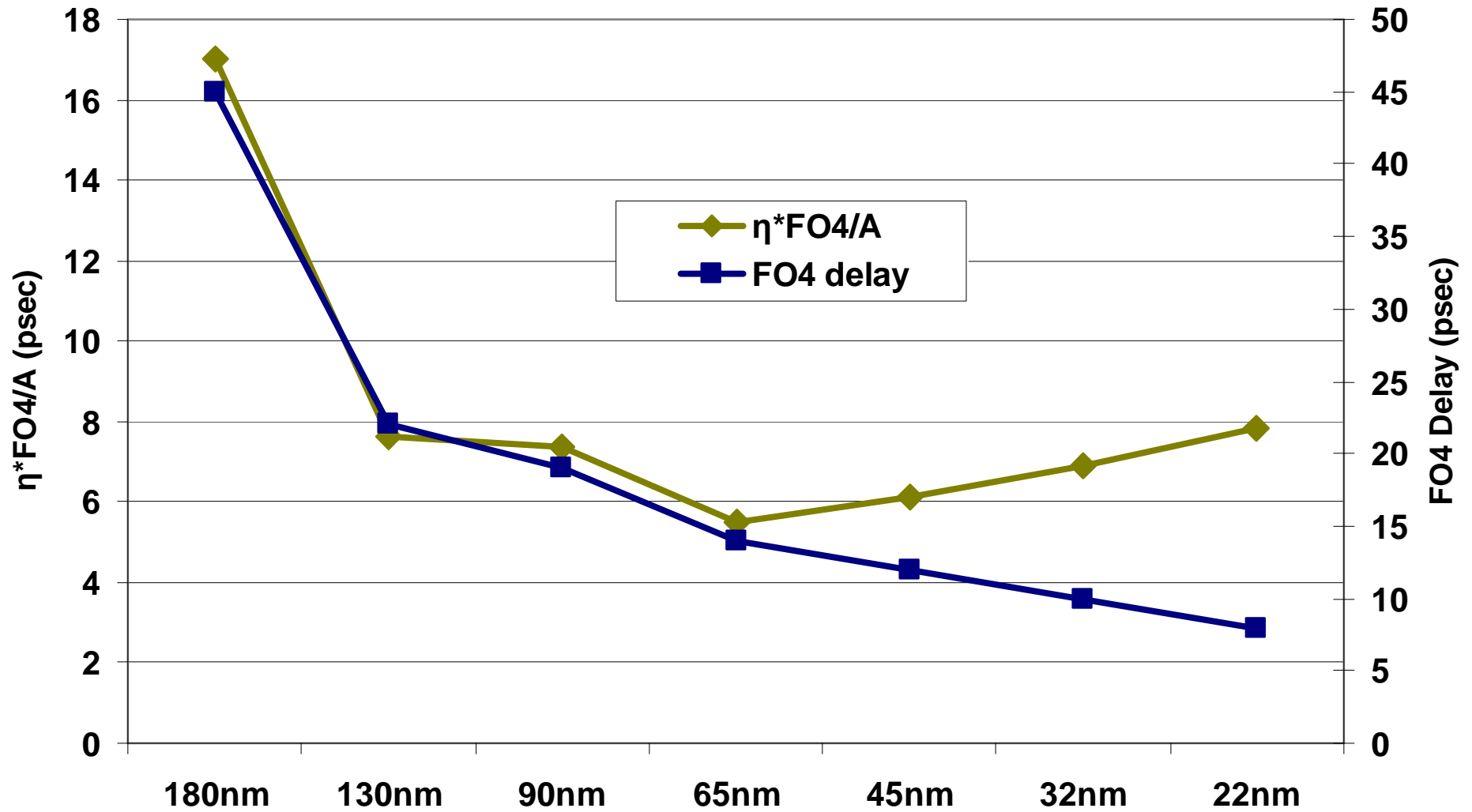
$$\tau = \frac{\eta FO4}{4 A}$$

Delay vs Gain tradeoff



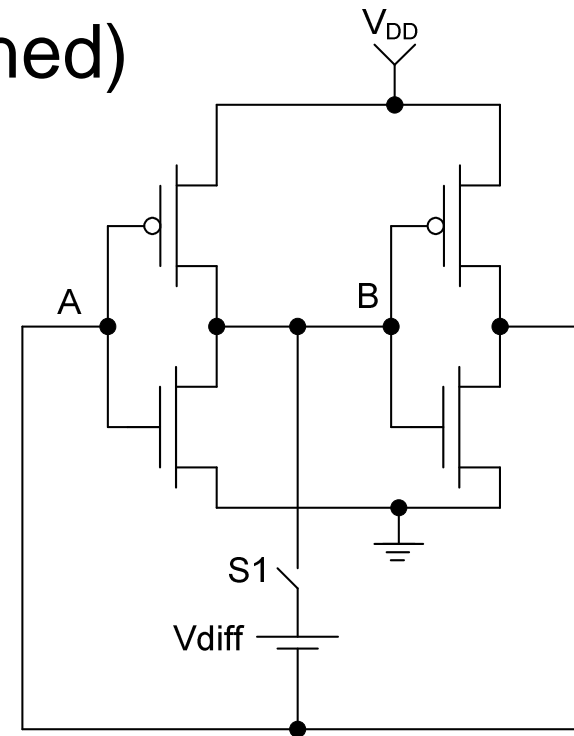
$$\tau = \frac{\eta FO4}{4 A}$$

Simulating η, A



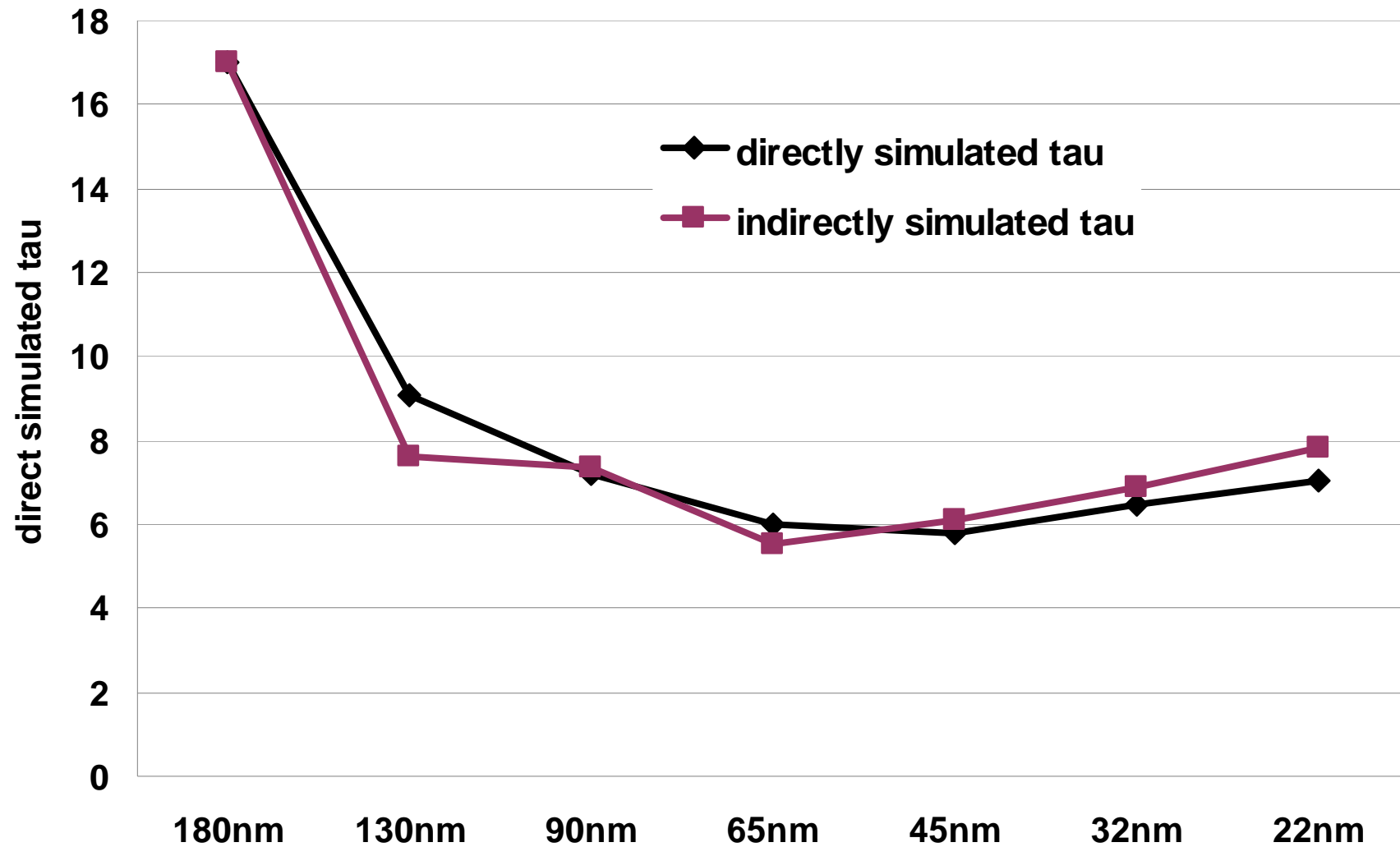
Direct simulations

- Latch is forced into metastability
 - S1 closed
- Switch (S1) is then released (opened)
- Latch resolves

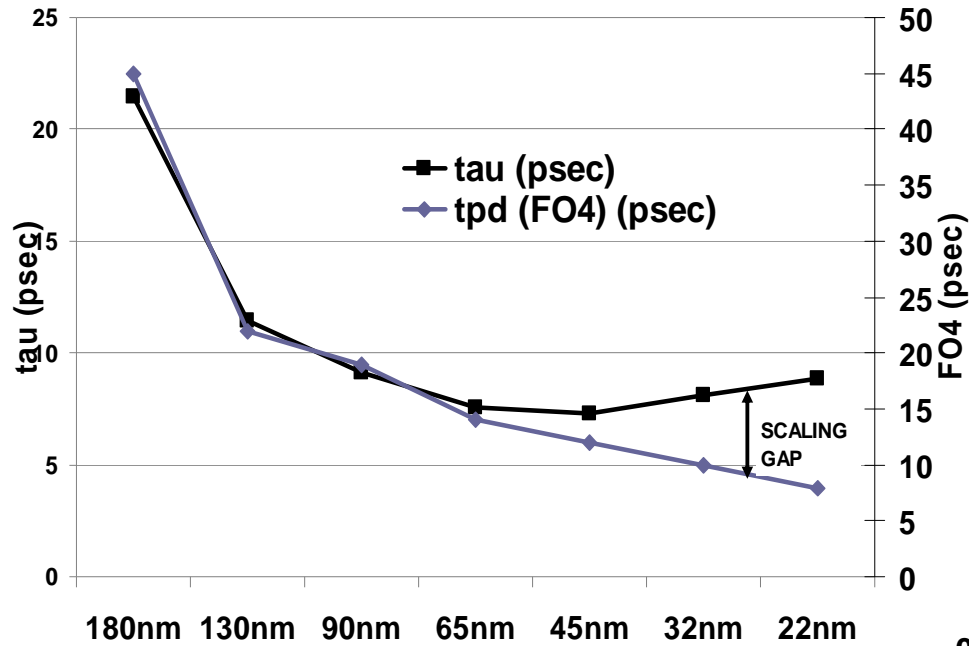


Dike and Burton (1999)

Direct and Indirect simulations

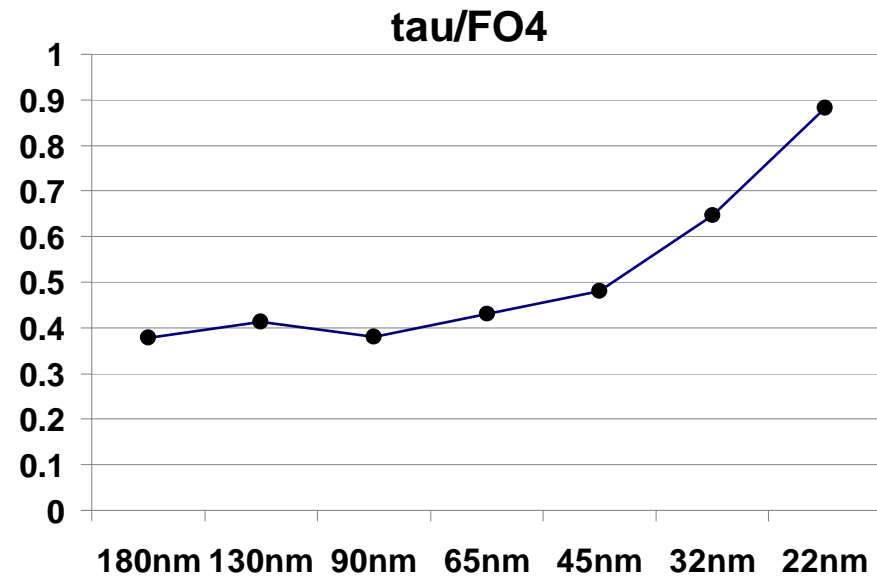


Simulation results

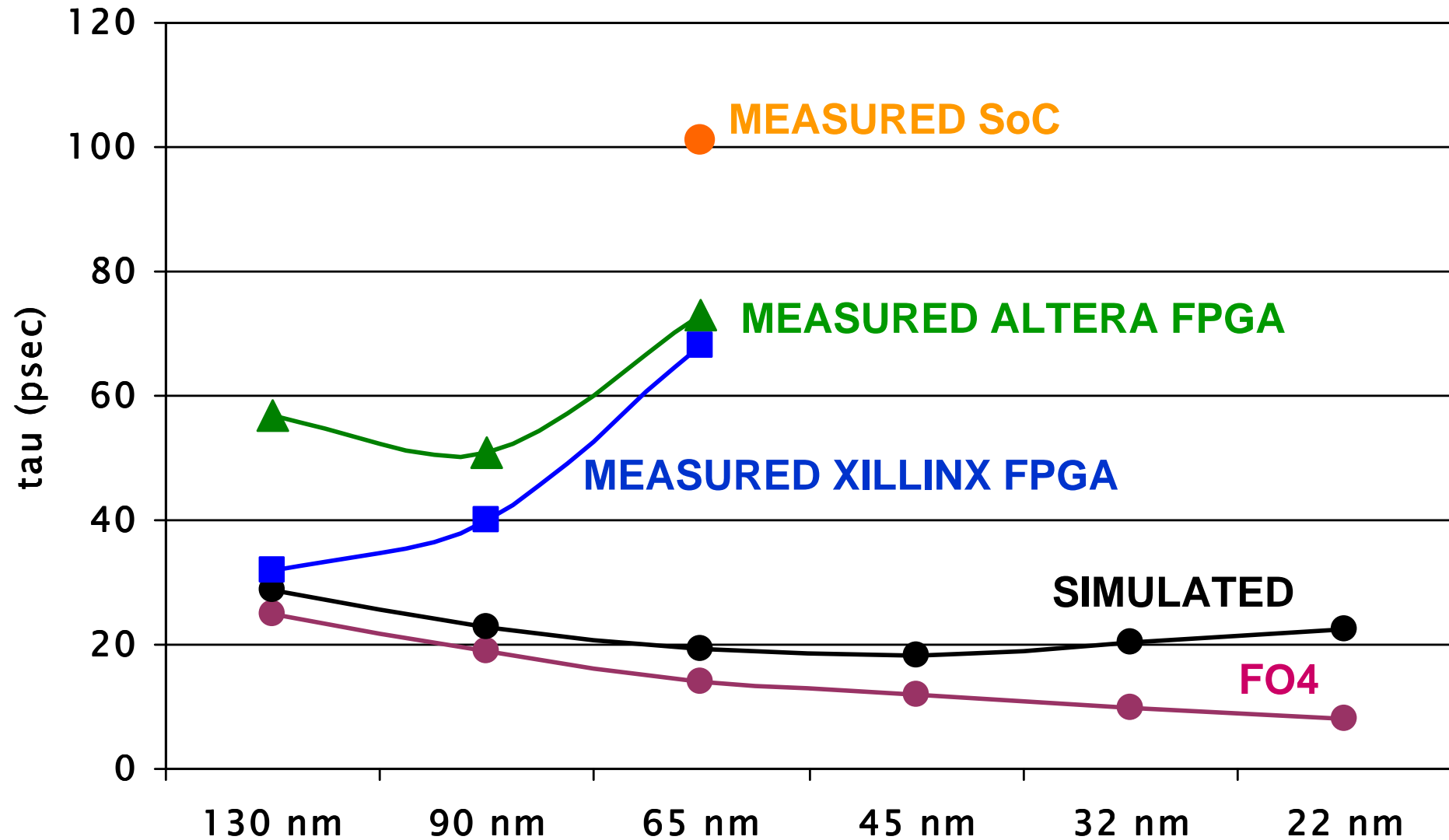


← scaling GAP

$$K = \frac{\tau}{FO4}$$



Unified graph of τ trend



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Remarks

- ▶ τ decreases until an inflection point and then increases with scaling.
- ▶ Inflection point:
 - Predicted :45nm node
 - Measured :65nm node
 } Optimistic model
- ▶ Different circuit design of FF \rightarrow trend
- ▶ Process flavors (GP, LP, HVT, LVT, etc.) affect τ
 - LP \rightarrow high FO4 \rightarrow high τ
 - GP \rightarrow low FO4 \rightarrow low τ
- ▶ Process Variations

New rule of thumb

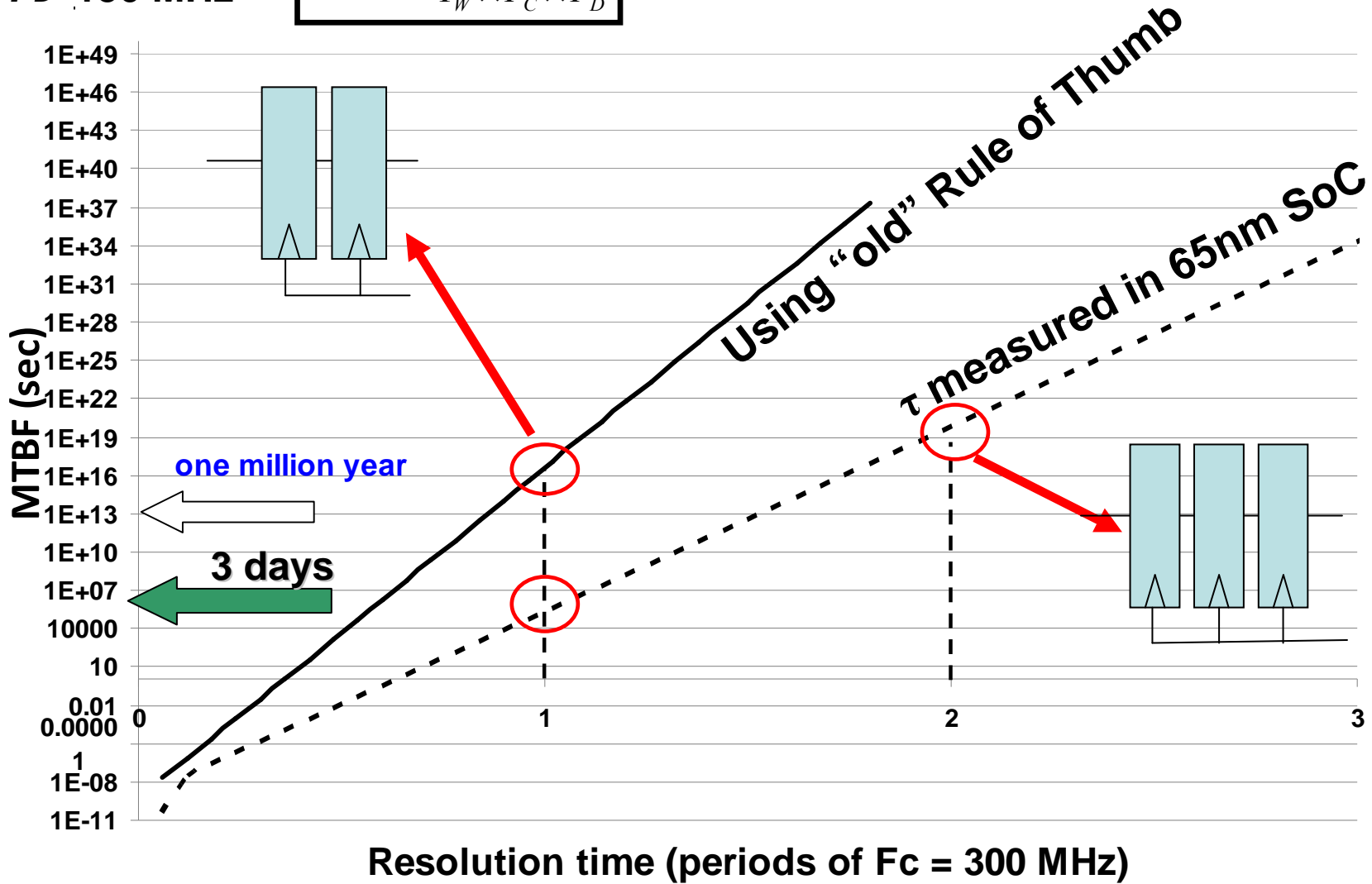
- ▶ No Rule of Thumb
- ▶ $\tau = \kappa \cdot FO4$, $K=2$ was good till 65nm tech.
- ▶ Future technologies will need characterization and adapted value of K .



Reliability example

$F_C=300$ MHz
 $F_D=150$ MHz

$$MTBF = \frac{e^{S/\tau}}{T_W \times F_C \times F_D}$$



Conclusions

- τ increases with scaling
 - τ degradation effect
- Three parameter Model
$$\tau = \frac{\eta FO4}{4 A}$$
- Simple rule of thumb fails
 - Don't re-use blindly
- *Characterize each process*

